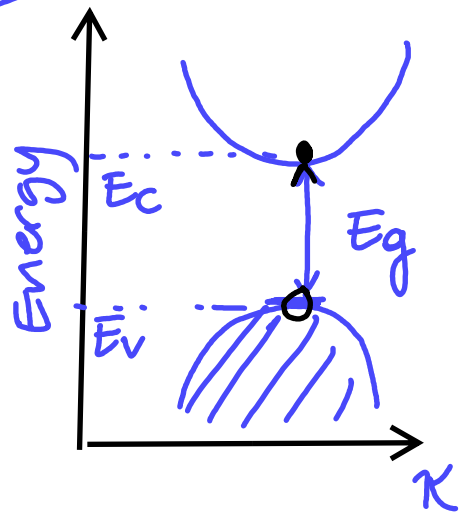


# Semiconductors

*Lecture 2*

# SEMICONDUCTORS

Recap

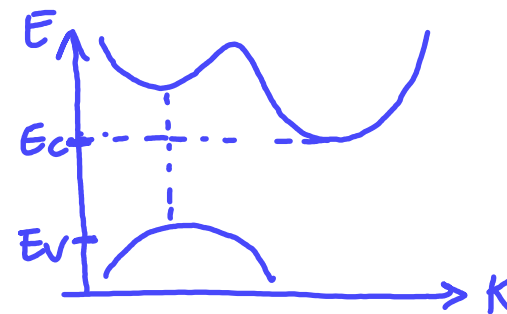


Conduction Band

Valence Band

↓ DIRECT BAND GAP

\* INDIRECT BAND GAP



Hole

$$\bar{k}_h = -\bar{k}_e$$

$$E_h(\bar{k}_h) = -E_e(\bar{k}_e)$$

$$\sigma_h = \sigma_e$$

$$m_h^* = -m_e^*$$

$$q_{\text{hole}} = +e$$

## Recap

- \* concentration of  $e^-$  in the C.B.  $n(T) \propto e^{-\frac{E_c - \mu}{k_B T}}$
- \* concentration of  $h^+$  in the V.B.  $p(T) \propto e^{-\frac{\mu - E_v}{k_B T}}$

\* Law of mass action  $n \cdot p = 4 \left( \frac{k_B T}{2\pi \hbar^2} \right) (m_e^* m_h^*)^{3/2} e^{-E_g / k_B T}$

$$E_g = E_c - E_v$$

\* Intrinsic semiconductor  $n_i = p_i$

$$\mu(T) = \frac{E_v + E_c}{2} + \frac{3}{4} k_B T \ln \frac{m_h^*}{m_e^*}$$



## Intrinsic mobility

Mobility.  $\mu_i = \frac{|\sigma|}{E}$

$$\left[ \frac{\text{m}^2}{\text{Vs}} \right]$$

do not confuse it with the chemical potential!

$\mu_i$  is defined positive for both e- and h!

- electric conductivity ( $\sigma = 1/\rho$ )

$$\sigma_e = \frac{j_e}{E} = \frac{n(T)e\sigma_e}{E} = n(T)e\mu_e$$

$$\sigma_h = \dots = p(T)e\mu_h$$

$$\sigma_{\text{TOTAL}} = \sigma_e + \sigma_h = n(T)e\mu_e + p(T)e\mu_h$$

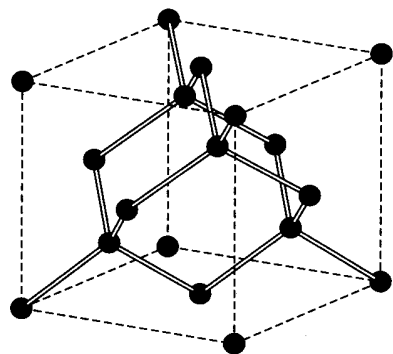
- drift velocity  $v = q\tau \frac{E}{m} \Rightarrow \mu_e = \frac{e\tau_e}{m_e}$  &  $\mu_h = \frac{e\tau_h}{m_h}$

$\tau$ : collision time

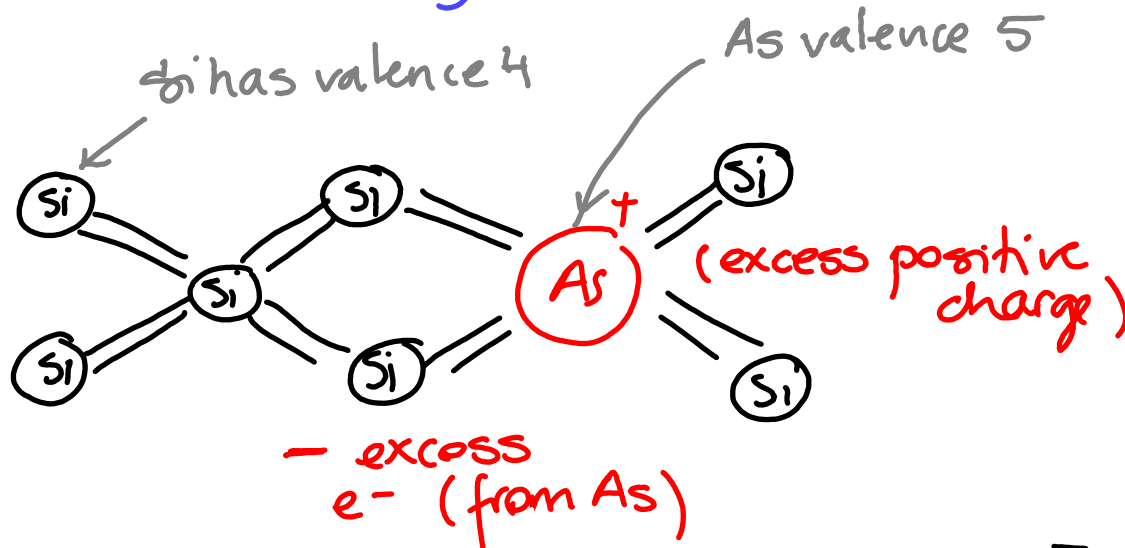
# Doping of semiconductors

Ex 0.001% of B in Si  $\rightarrow$  conductivity  $\times 1000$ !

13 IIIA	14 IVA	15 VA
5 B Boron 10.81 2.2	6 C Carbon 12.01 2.4	7 N Nitrogen 14.01 3.5
13 Al Aluminum 26.98 3.0	14 Si Silicon 28.09 3.4	15 P Phosphorus 30.97 3.5
31 Ga Gallium 69.72 3.0-3.2	32 Ge Germanium 72.63 3.4-3.6	33 As Arsenic 74.92 3.5-3.6
49 In Indium 114.82 3.0-3.2	50 Sn Tin 118.71 3.0-3.4	51 Sb Antimony 121.76 3.0-3.5



Diamond structure  
(Si, Ge)



$\Rightarrow$  semiconductor type-n  
As = Donor ( $e^-$ )

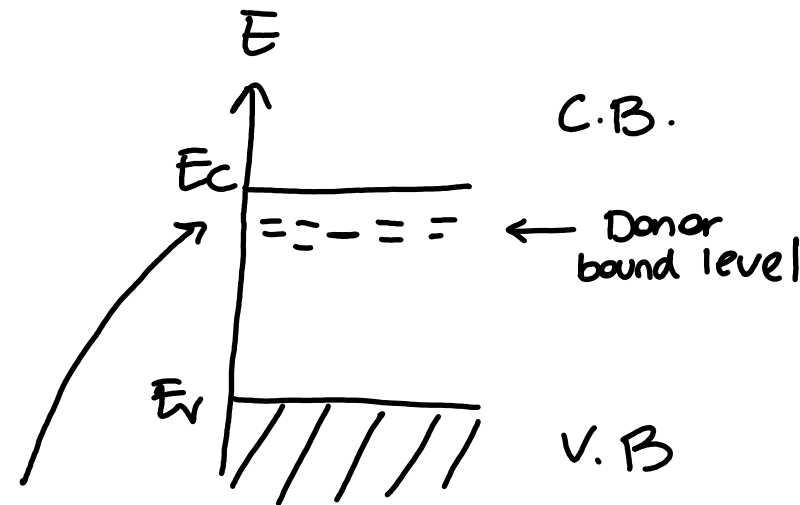
Where is the energetic level of the impurity?

Hydrogen atom  $E_{ion} = -\frac{e^4 m}{2(4\pi\epsilon_0 \hbar)^2} = 13.6 \text{ eV}$

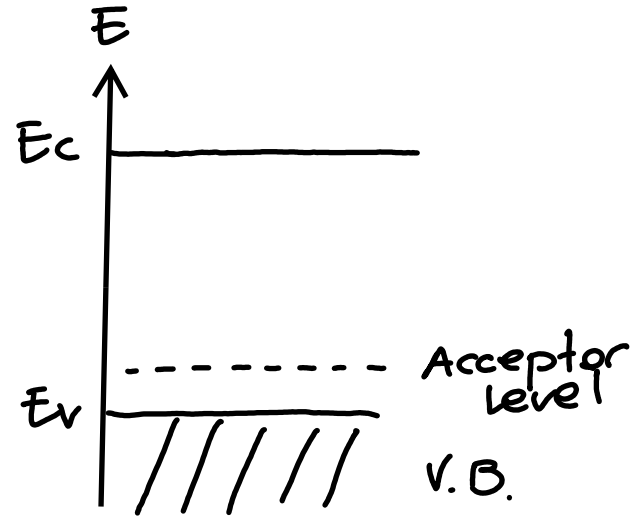
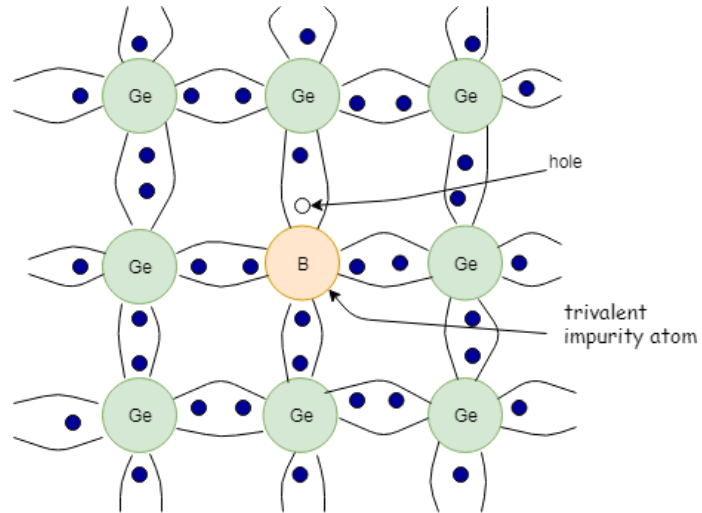
$E_c - E_{donor} = \frac{e^4 m_e^*}{2(4\pi\epsilon_0 \hbar)^2} \sim 10 \text{ meV}$

$E \sim 10$   
 $m_e^* \sim 0.1 m_e$

Donor impurity forms an energy eigenstate just below the bottom of C.B.



# Acceptors



Doping type - p : the doped semiconductor has excess of holes

# Nomenclature

Type n: carriers are free  $e^-$  in the conduction band given at RT by ionized donors

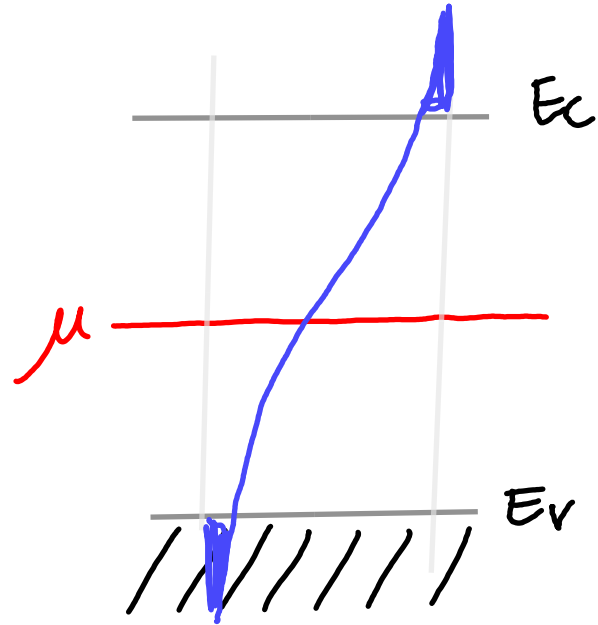
Type p: carriers are free holes in the valence band given at RT by ionized acceptors

Intrinsic: pure semiconductor,  $n = p$  without doping

For all  $n$  and  $p$ ,  $np$  only depends on:

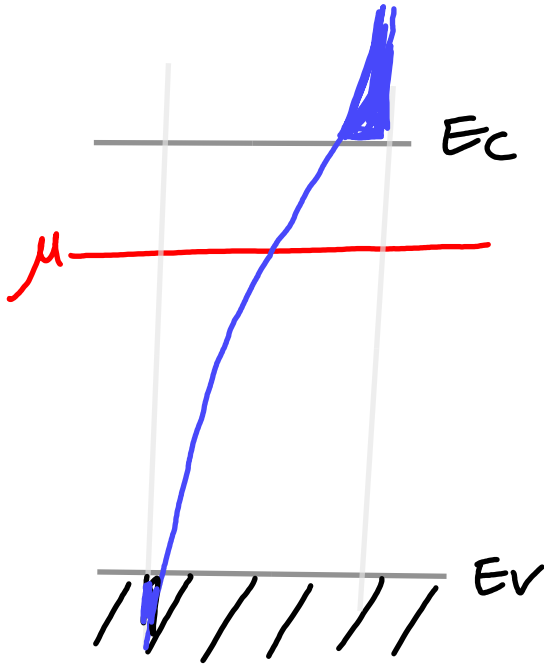
- intrinsic material
- temperature

Ferui level changes if one modifies the balance  $n, p$



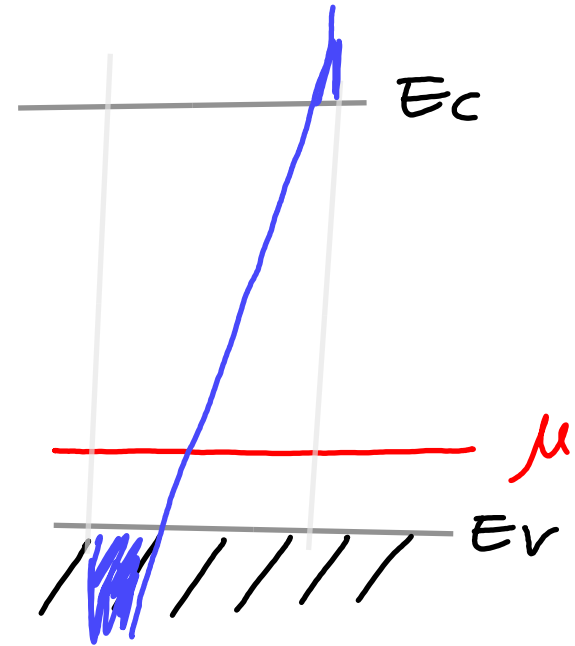
$$n=p$$

absence of impurities,  
the Fermi level (chemical  
potential at 0K) is in the  
middle of the gap



$$n > p$$

Donnors

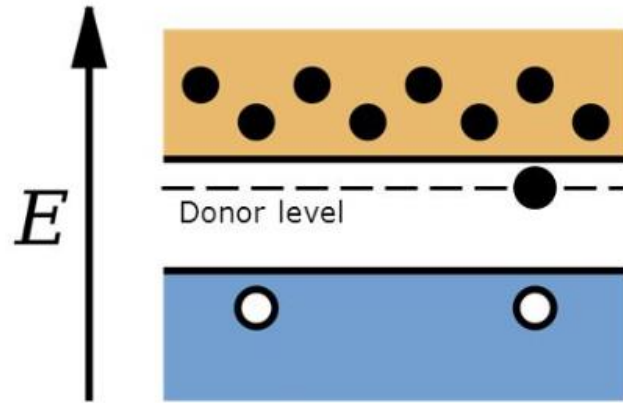


$$n < p$$

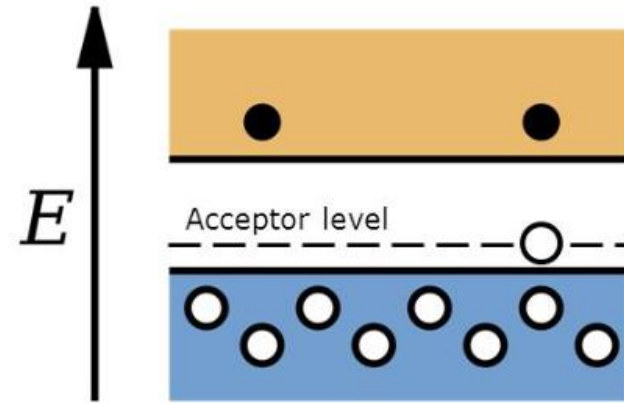
Acceptors



*n*-type band structures :



*p*-type band structures :



Group IV semiconductors:

Si and Ge  
Donors: P and As

Group III-V semiconductors:

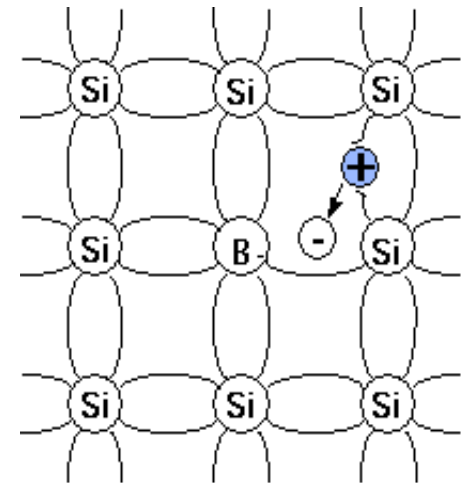
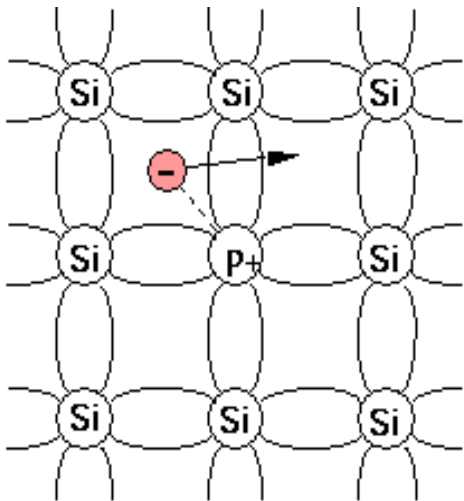
GaAs and GaN  
Donors: Se, Te, Si and Ge

Group IV semiconductors:

Si and Ge  
Acceptors: B and Al

Group III-V semiconductors:

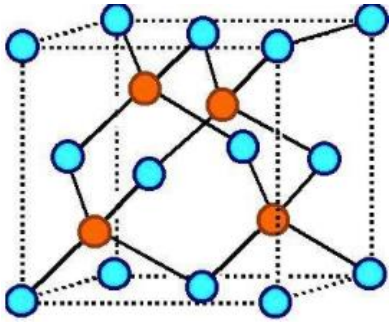
GaAs and GaN  
Acceptors: Be, Zn, Cd and Ge



Semiconductor devices

# Band structure engineering

## Designing band gaps



zinc blende structure

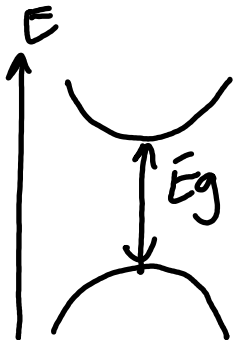
$$\text{GaAs} - E_{\text{gap}} = 1.4 \text{ eV}$$

$$\text{AlAs} - E_{\text{gap}} = 2.7 \text{ eV}$$



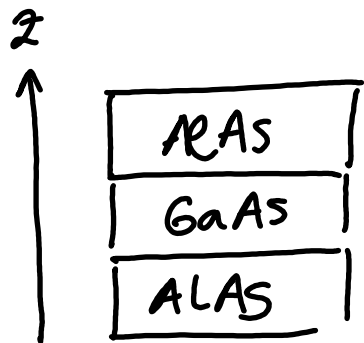
$$E_{\text{gap}}(x) = (1-x) 1.4 \text{ eV} + x 2.7 \text{ eV}$$

As first approx., the direct band gap interpolates those of GaAs and AlAs



Semiconductor lasers  
(520nm, 445nm, 635nm)

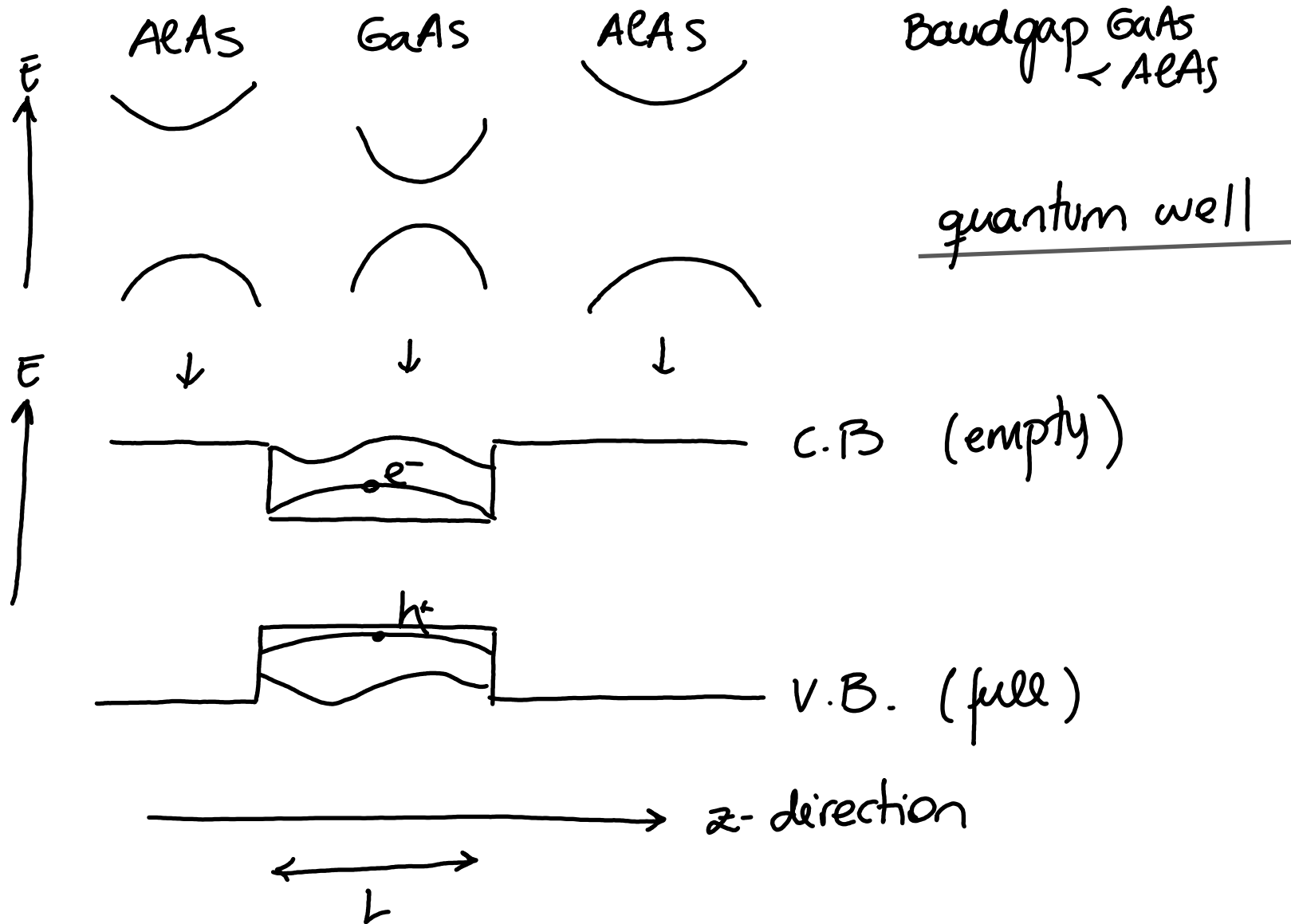
# Non-homogeneous band gaps



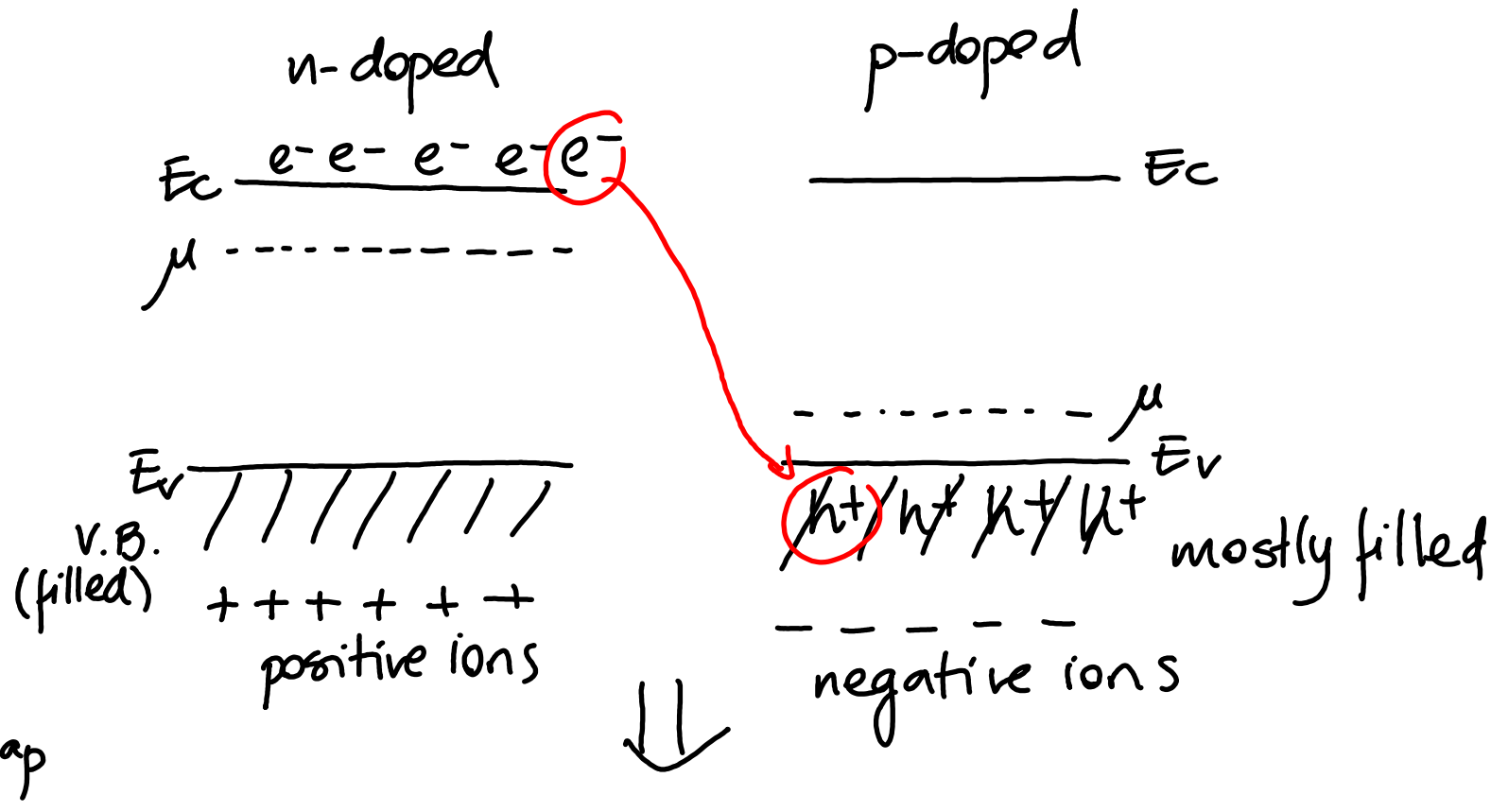
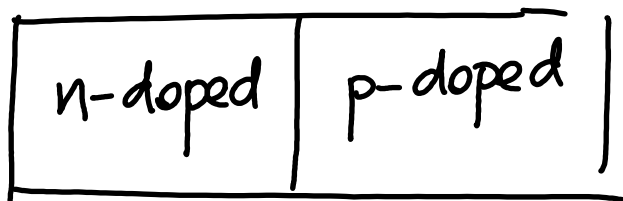
heterostructure

$e^-$  in a semiconductor see the energy in the c.b. bottom as a potential as function of position in which they can be trapped.

(idea for holes and top of the v.b.)

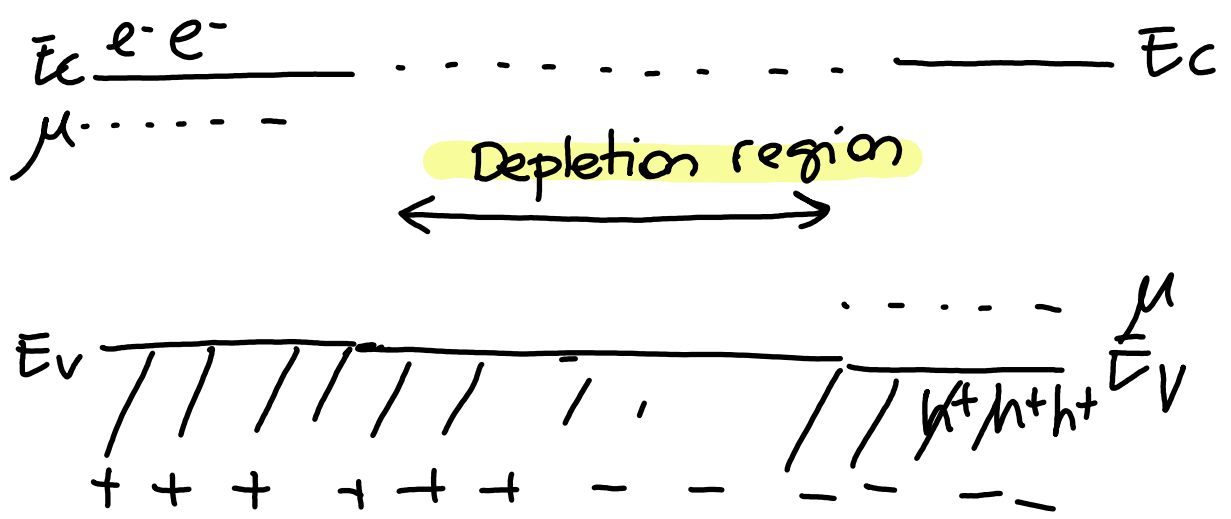


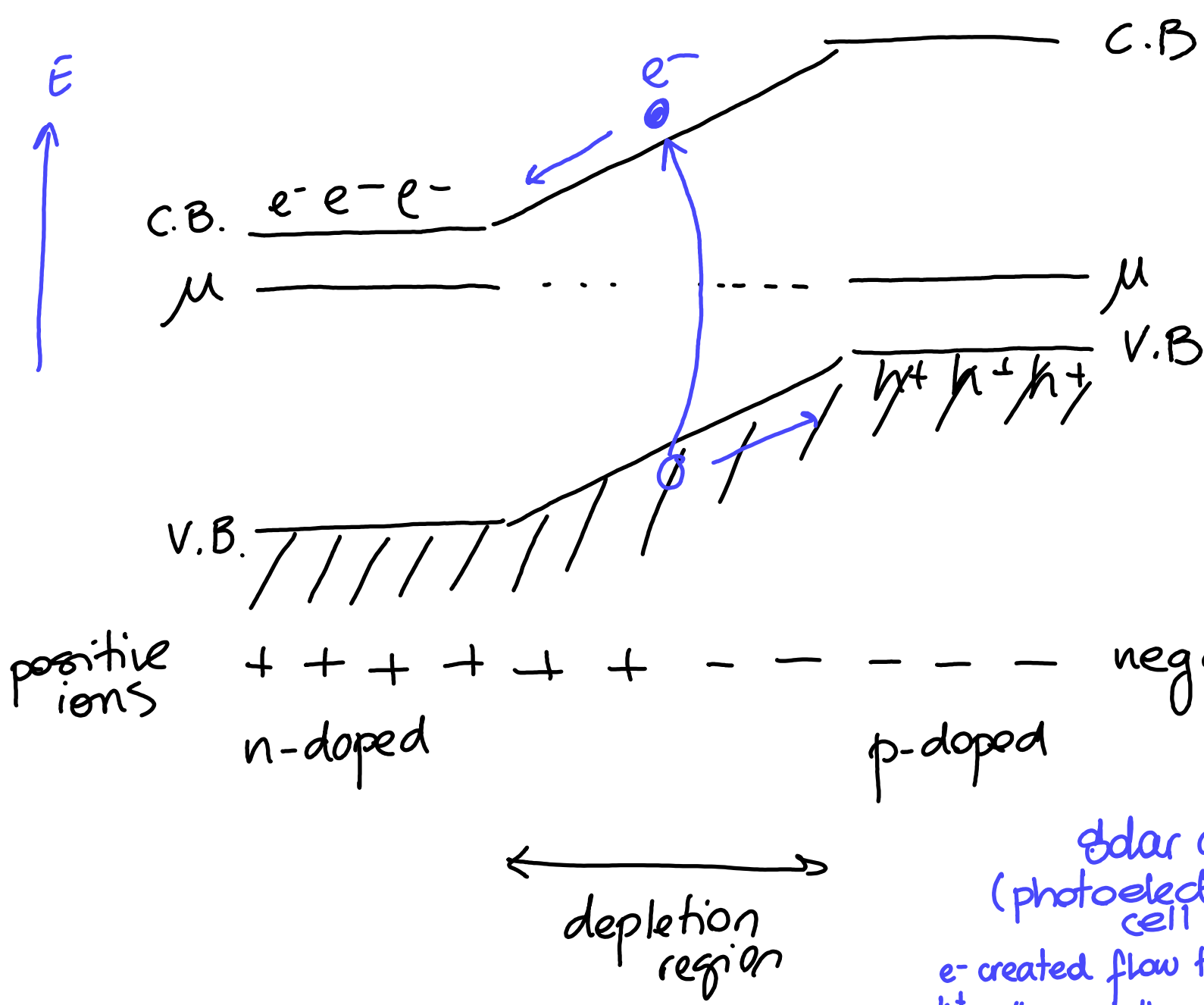
# p-n Junction



When the 2 materials are brought together,  $e^-$  in c.B. will fall in the v.B. to annihilate holes  
 → this annihilating process gains an energy  $E_{gap}$

As a result, there will be a region close to the interface where there are no more free carriers  
 ⇒ "depletion region" or "space charge region"





Due to annihilating processes, there are no more free carriers in the depletion region, but the negative and positive charged ions still remain there

∴ now a net electric field

If one  $e^-$  wants to cross this region to annihilate a  $h^+$ , it has an energy cost to overcome  $-e\Delta\phi$  electrostatic potential

∴ Depletion region width determined by energy compensation  
 $E_g = e\Delta\phi$

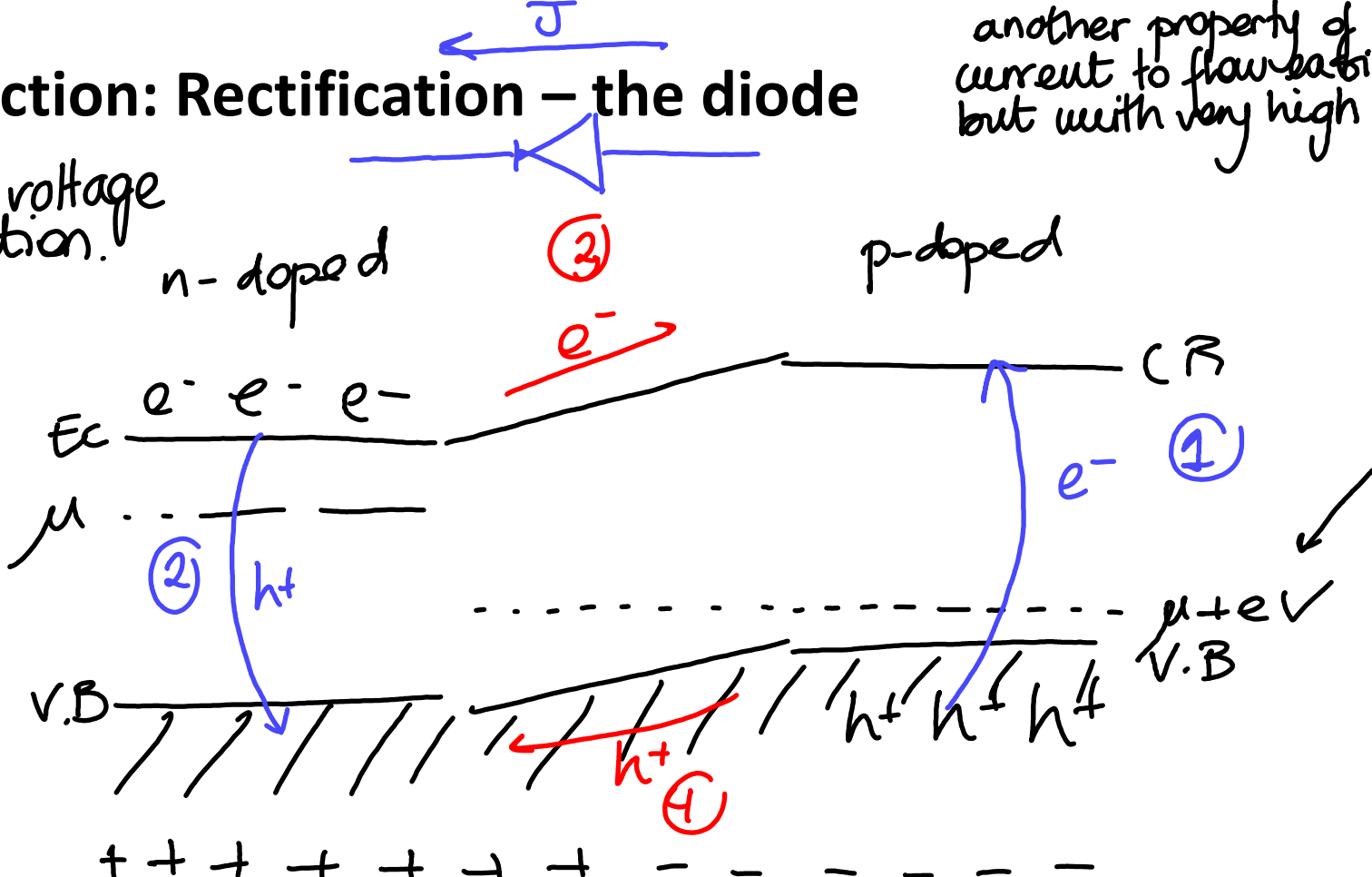
Solar cell: put in photons → get current  
 (photoelectric cell)

$e^-$  created flow to the left (n-doped)  
 $h^+$  " " " " right (p-doped) } In both cases, current is moving to the right

# p-n Junction: Rectification – the diode

another property of p-n junctions: allows current to flow easily in one direction but with very high  $R$  in the other

Let's apply a voltage to a pn junction.



bend downwards due to the applied voltage

## Processes that can create current

①, ② # of carriers: typically activated form  $\sim e^{-E_g/K_B T}$  :  $I_{right} \propto e^{-E_{gap}/K_B T}$

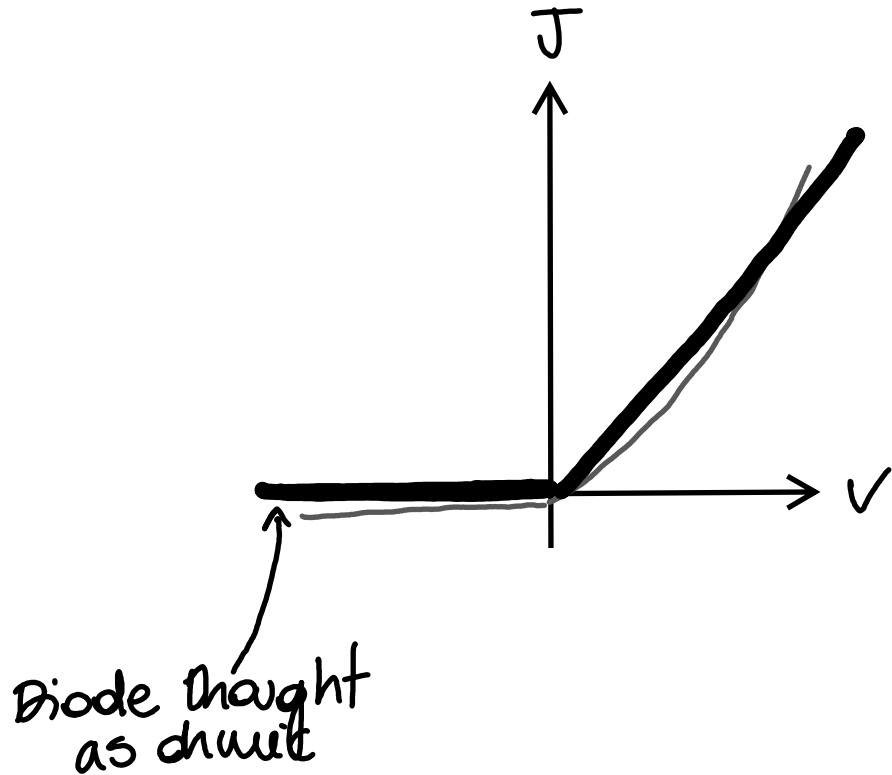
③, ④  $e^-$  in the CB at n-doped side (left diagram) might be thermally activated to climb slope in the depletion region, and then annihilated with  $h^+$  at p-side  
 If voltage applied, height potential becomes  $E_g + eV \Rightarrow$  current of these processes  $I_{left} \propto e^{-\frac{(E_{gap} + eV)}{K_B}}$

idem with holes

Total current  $J_{\text{left}} + J_{\text{right}}$ , and taking into account that  $J(V=0)=0$ :

$$J \sim \underbrace{e^{-\frac{E_{\text{gap}}}{k_B T}}}_{J_s = \text{saturation current}} \left( e^{-\frac{eV}{k_B T}} - 1 \right)$$

DIODE EQUATION



Symbol (current flows easy in the arrow direction)

